

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3836053

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the EXECUTION DATE previously recorded on Reel 038090 Frame 0190. Assignor(s) hereby confirms the ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
SRAVAN KUMAR AMBAPURAM	01/05/2015
KRISHNA V.S.S.S.R. VANKA	01/05/2015
MURALI NALAJALA	10/20/2015
SHIRISH KUMAR AGARWAL	01/05/2015
NIKHIL KUMAR KANSAL	01/05/2015
RECEIVING PARTY DATA	
Name:	QUALCOMM INNOVATION CENTER, INC.
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14629216
CORRESPONDENCE DATA	
Fax Number:	(720)536-4910
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	720.536.4900
Email:	rene@nodiqlaw.com
Correspondent Name:	NEUGEBOREN O'DOWD PC
Address Line 1:	1227 SPRUCE STREET
Address Line 2:	SUITE 200
Address Line 4:	BOULDER, COLORADO 80302
ATTORNEY DOCKET NUMBER:	141470
NAME OF SUBMITTER:	SEAN R. O'DOWD
SIGNATURE:	/Sean R. O'Dowd/
DATE SIGNED:	04/19/2016

Total Attachments: 7

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3798370

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SRAVAN KUMAR AMBAPURAM	01/15/2016
KRISHNA V.S.S.S.R. VANKA	01/05/2016
MURALI NALAJALA	10/20/2015
SHIRISH KUMAR AGARWAL	01/05/2016
NIKHIL KUMAR KANSAL	01/05/2016
RECEIVING PARTY DATA	
Name:	QUALCOMM INNOVATION CENTER, INC.
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14629216
CORRESPONDENCE DATA	
Fax Number:	(720)536-4910
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	720.536.4900
Email:	rene@nodiplay.com
Correspondent Name:	NEUGEBOREN O'DOWD PC
Address Line 1:	1227 SPRUCE STREET
Address Line 2:	SUITE 200
Address Line 4:	BOULDER, COLORADO 80302
ATTORNEY DOCKET NUMBER:	141470
NAME OF SUBMITTER:	SEAN R. O'DOWD
SIGNATURE:	/Sean R. O'Dowd/
DATE SIGNED:	03/24/2016
Total Attachments: 6	

ASSIGNMENT

WHEREAS, WE,

1. **Sravan Kumar Ambapuram**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
2. **Krishna V.S.S.R. Vanka**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
3. **Murali Nalajala**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
4. **Shirish Kumar Agarwal**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
5. **Nikhil Kumar Kansal**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SUSPEND AND RESUME TIMELINE OPTIMIZATION FOR APPLICATION PROCESSOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Qualcomm Innovation Center, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/629,216 filed February 23, 2015, Qualcomm Reference No. 141470, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States:

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hyderabad, on 1/5/2015
LOCATION DATE

A. Sridhar
Sruvan Kumar Ambapuram

Done at Hyderabad, on 1/5/2015
LOCATION DATE

V.V.S.S.R. Vanka
Krishna V.S.S.R. Vanka

Done at _____, on _____
LOCATION DATE

Murali Nalajala

Done at HYDERABAD, on 1/5/2015
LOCATION DATE

Agarwal
Shirish Kumar Agarwal

Done at HYDERABAD, on 1/5/2015
LOCATION DATE

Nikhil Kumar Kansal
Nikhil Kumar Kansal

ASSIGNMENT

WHEREAS, WE,

1. **Sravan Kumar Ambapuram**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
2. **Krishna V.S.S.S.R. Vanka**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
3. **Murali Nalajala**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
4. **Shirish Kumar Agarwal**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,
5. **Nikhil Kumar Kansal**, a citizen of India (IN), having a mailing address located at Qualcomm Incorporated, 5775 Morehouse Drive, San Diego, CA 92121, and a resident of Hyderabad, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SUSPEND AND RESUME TIMELINE OPTIMIZATION FOR APPLICATION PROCESSOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Qualcomm Innovation Center, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/629,216 filed February 23, 2015, Qualcomm Reference No. 141470, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part

applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE

Srayan Kumar Ambapuram

Done at _____, on _____
LOCATION DATE

Krishna V.S.S.R. Vanka

Done at San Diego, on 10/20/2015
LOCATION DATE



Murali Nalajala

Done at _____, on _____
LOCATION DATE

Shirish Kumar Agarwal

Done at _____, on _____
LOCATION DATE

Nikhil Kumar Kansal